



FOR IMMEDIATE RELEASE

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**AEHR TEST SYSTEMS INTRODUCES  
FULL WAFER CONTACT BURN-IN AND PARALLEL TEST SYSTEM**

**Fremont, CA (July 12, 2001)** – Aehr Test Systems (Nasdaq: AEHR), a leading provider of burn-in and parallel test solutions for DRAMs and other integrated circuits, announced today it will introduce its FOX™ Full Wafer Contact system during Semicon West 2001. The FOX system is designed to make contact with all pads of a wafer simultaneously, thus enabling full wafer burn-in and parallel test. The FOX system is applicable to a wide range of semiconductor wafers.

In June, Aehr Test Systems announced the first order for its FOX wafer-level burn-in contactor for laser diodes, which will be used in a wafer-level burn-in system. This represents the first phase of a development partnership between Aehr Test and a manufacturer of VCSELs, or vertical cavity surface emitting lasers.

VCSELs are used in high-speed local-area data communications, and represent the latest technology in semiconductor laser diodes. The market for semiconductor lasers is projected by industry analysts to have a compound annual growth rate of greater than 40% over the next few years.

One of the key features of the FOX system is the patent-pending cartridge system. This unique design is intended to accommodate a wide range of contactor technologies. "No single contact technology is best for all applications," said C.J. Meurell, president and chief operating officer of Aehr Test. "The most cost-effective contactor for VCSELs is not necessarily the best contactor for doing flip-chip DRAM memory testing, full wafer contact FLASH testing or microprocessors. Our design allows us to match the best contactor to the customer's needs," Meurell added.

"This is a great opportunity for Aehr Test to expand into new markets. We have leveraged our micro-interconnect technology and our massively parallel burn-in and test equipment into a fully parallel wafer burn-in and test system," said Rhea Posedel, chairman and chief executive officer of Aehr Test. "We have had strong customer interest in this concept. Customers have been contacting us with even more applications than we had previously pursued," Posedel added.



*Aehr Test Systems Announces its FOX, Full Wafer Contact system*

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In January of this year, Aehr Test completed a \$6.5 million multi-year research and development agreement with the U.S. Defense Advanced Research Projects Agency (DARPA) to develop a wafer-level burn-in and test system for memories and other ICs. Wafer-level burn-in and test enables lower cost production of Known-Good Die (KGD) for multi-chip modules and systems-in-a-package.

Further information about the FOX Full Wafer Contact system will be available at the Aehr Test Systems booth, #10727, during Semicon West, July 18-20 at the San Jose Convention Center in San Jose, CA. Those interested in a demonstration of the FOX system should contact Chris Noe, vice-president of sales, at Aehr Test (510-623-9400), or register through Aehr Test's web site ([www.aehr.com](http://www.aehr.com)), prior to Semicon West. The first shipment of FOX systems is expected within one year.

### **About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a leading provider of systems for burning-in and testing DRAM and logic integrated circuits and has an installed base of more than 2,000 systems worldwide. Aehr Test has developed and introduced several innovative products, including the FOX, MTX and MAX3 systems and the DiePak® carrier. The FOX is a full wafer contact burn-in and test system. The MTX is a massively parallel test system designed to reduce the cost of memory testing by performing both test and burn-in on thousands of devices simultaneously. The MAX3 can effectively burn-in and functionally test sophisticated devices, such as digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die.

### **Safe Harbor Statement**

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding industry growth and customer demand for the Company's products. Actual results may vary from projected results. These risks and uncertainties include economic conditions in Asia and elsewhere, acceptance by customers of the MTX, MAX and DiePak technologies, the Company's development and manufacture of a commercially successful wafer-level burn-in system, and the potential emergence of alternative technologies, which could adversely affect demand for the Company's products in fiscal year 2002. See the Company's 10-K and 10-Q reports filed with the SEC for additional risks affecting the Company.

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